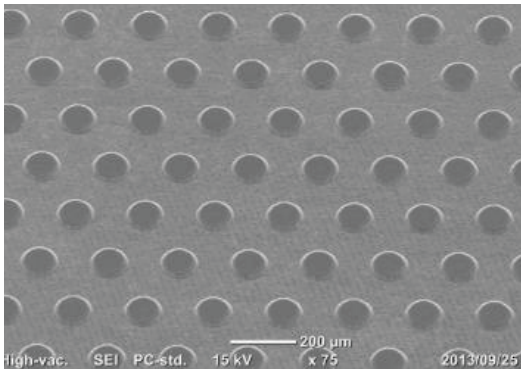
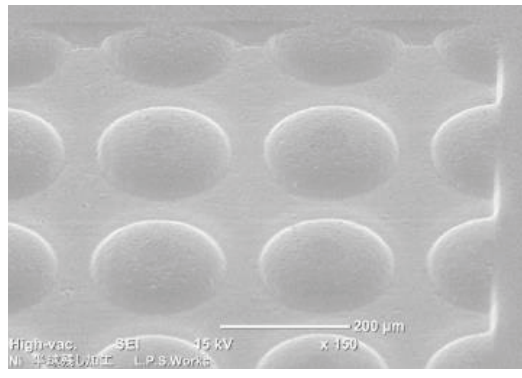


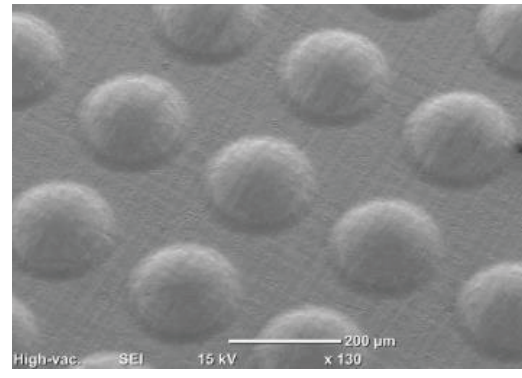
● Embossing



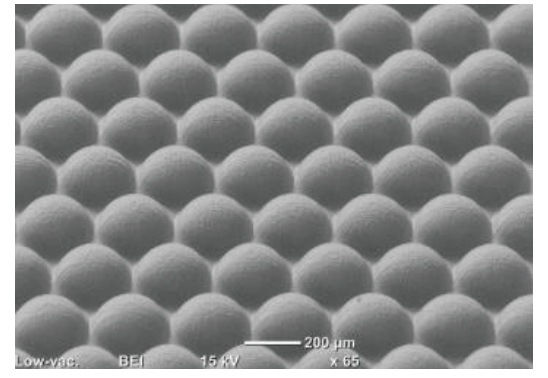
Material :SUS430
Diameter :100 μ m
Height :12 μ m



Material :Ni
Diameter :200 μ m
Height :30 μ m

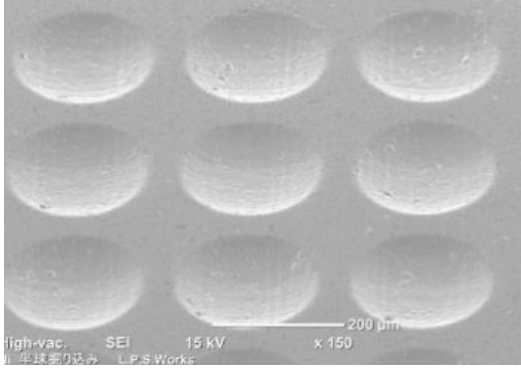


Material :SUS304
Diameter :200 μ m
Height :30 μ m

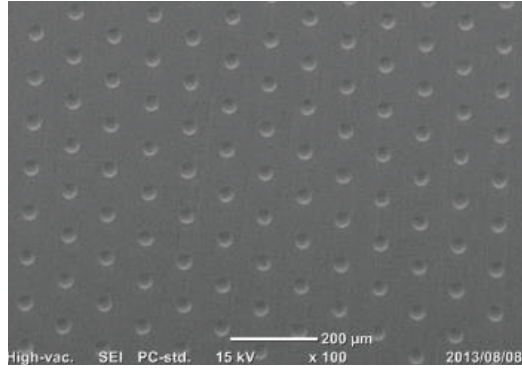


Material :Borosilicate glass
Diameter :250 μ m
Height :125 μ m

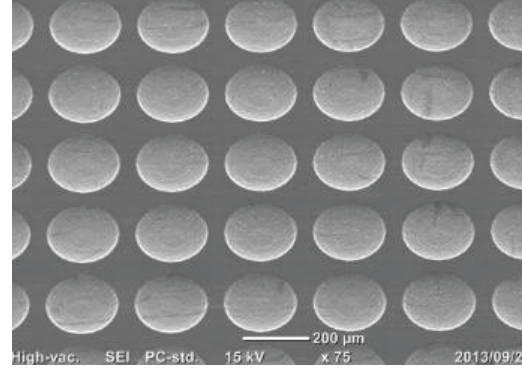
● Dimple processing



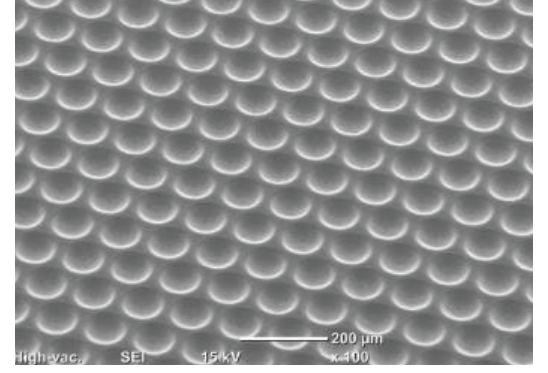
Material :Ni
Hole diameter : Φ 200 μ m
Pitch :250 μ m



Material :Cu
Hole diameter : Φ 35 μ m
Pitch :100 μ m

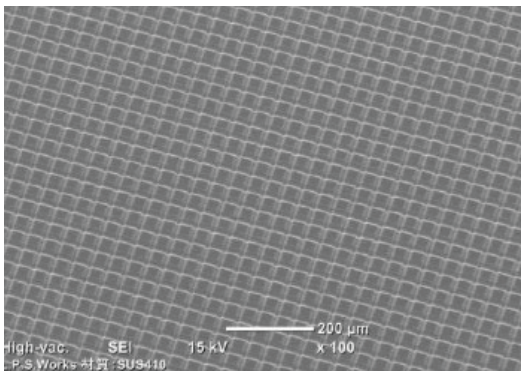


Material :Al
Hole diameter : Φ 200 μ m
Pitch :250 μ m

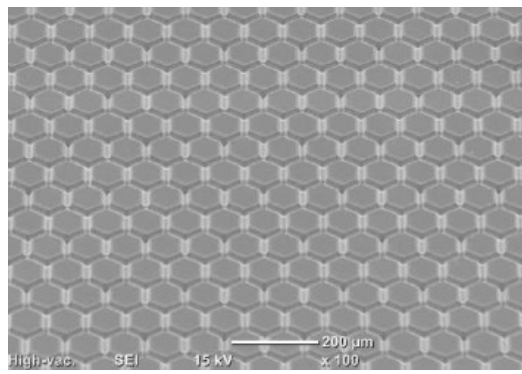


Material :SUS430
Hole diameter : Φ 95 μ m
Pitch :110 μ m

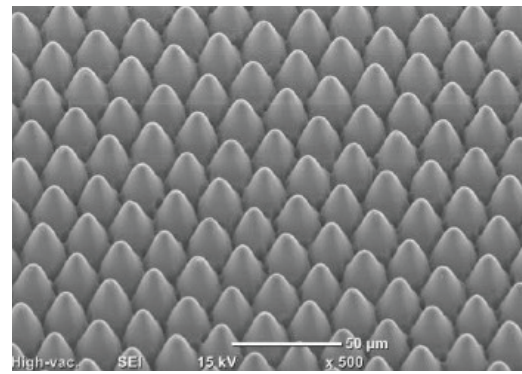
● Lattice groove processing



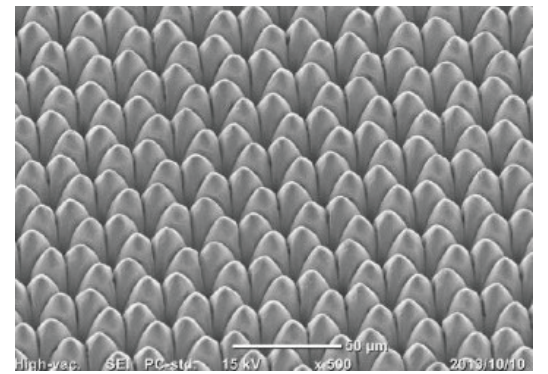
Material :SUS410
L/S :20 μ m
Groove depth :2 μ m



Material :SUS304
Side length :50 μ m
Groove depth :10 μ m

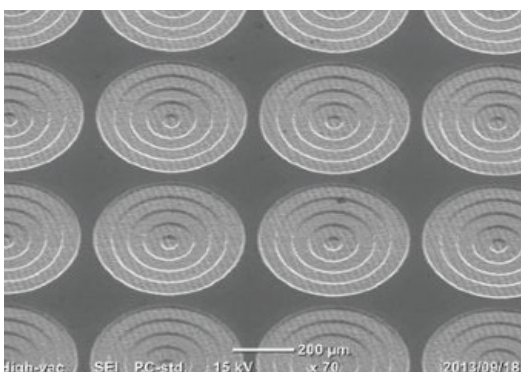


Material :SUS430
Height :20 μ m
Pitch :20 μ m

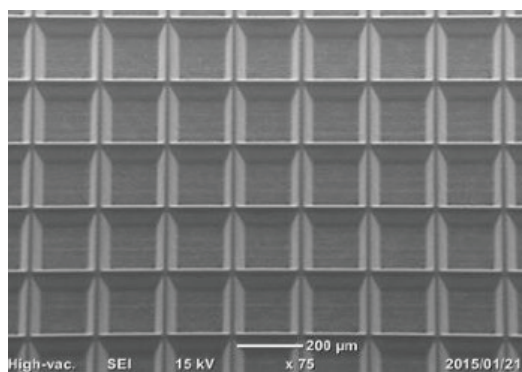


Material :SUS430
Side length :15 μ m
Groove depth :17 μ m

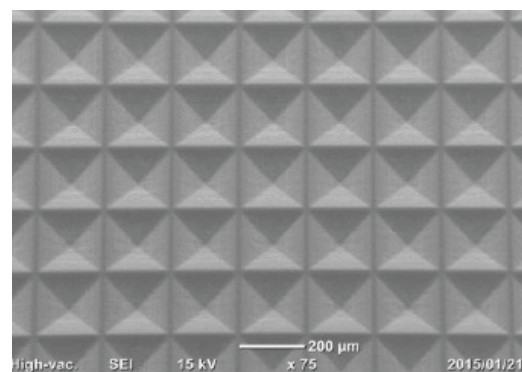
● Three-dimensional shapes processing



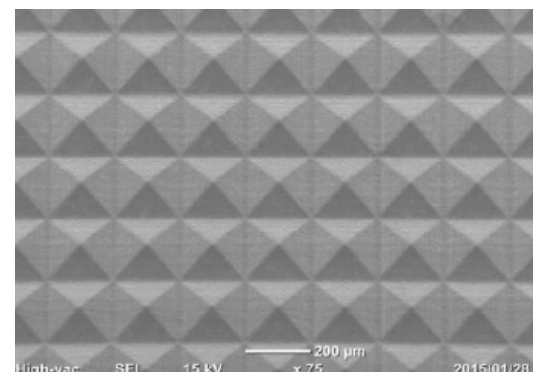
Material :Aluminum
Hole diameter :50,150,250,350,450 μ m
Height dimensions :6 μ m for each stage



Material :SUS304
Dimensions :200 μ m
Depth :50 μ m

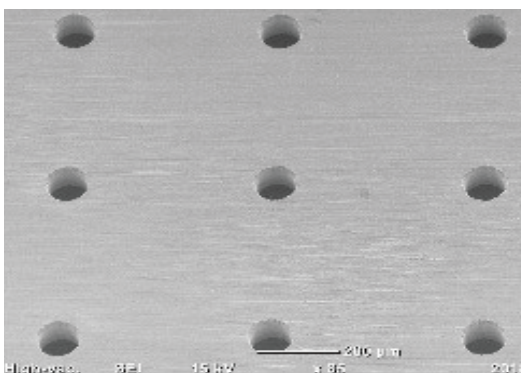


Material :SUS304
Dimensions :190 μ m
Center depth :50 μ m

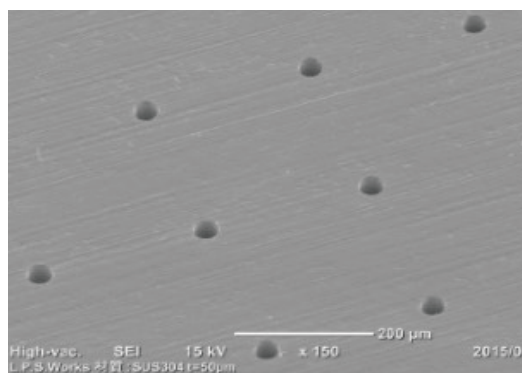


Material :SUS304
Dimensions :190 μ m
Center height :50 μ m

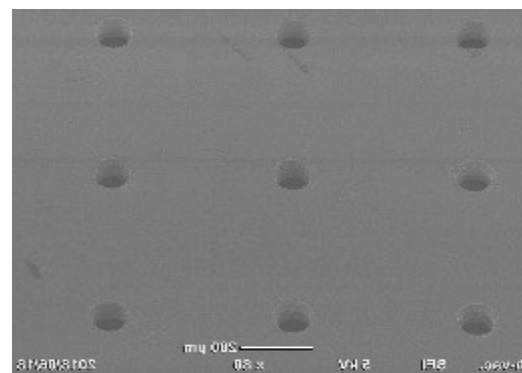
● Micro straight through hole processing



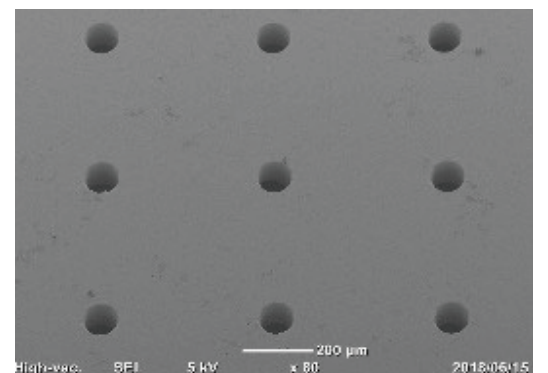
Material :Cu
Hole diameter : Φ 50 μ m
Thickness :100 μ m



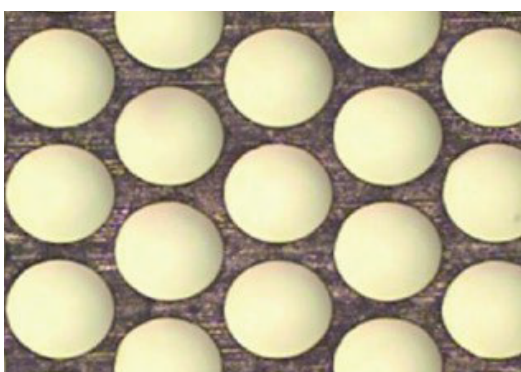
Material :SUS304
Hole diameter : Φ 50 μ m
Thickness :50 μ m



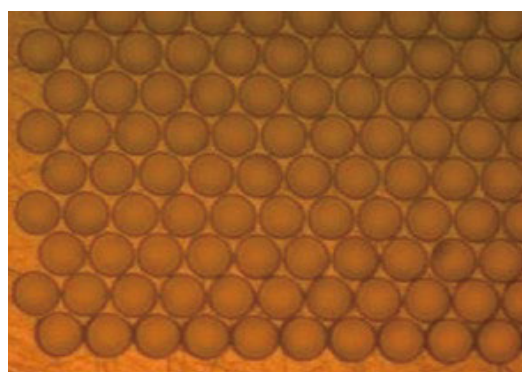
Material :Aluminum
Hole diameter : Φ 50 μ m
Thickness :100 μ m



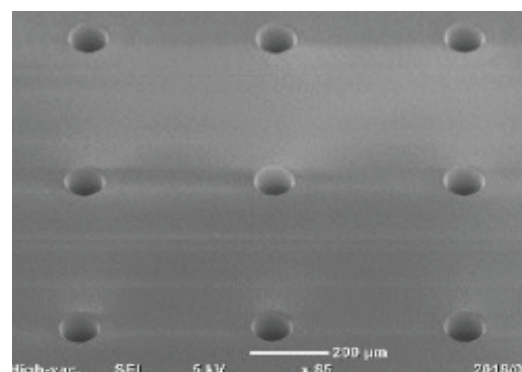
Material :Molybdenum
Hole diameter : Φ 50 μ m
Thickness :125 μ m



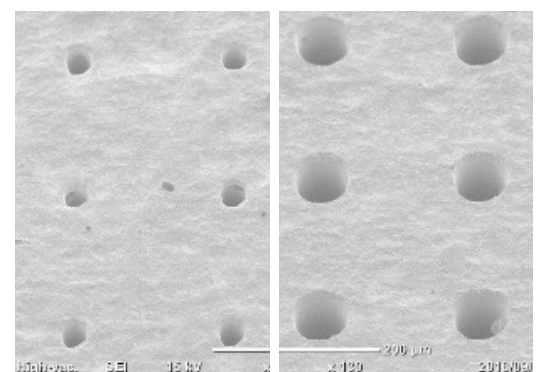
Material :Silicon Nitride
Hole diameter : Φ 100 μ m
Thickness :200 μ m



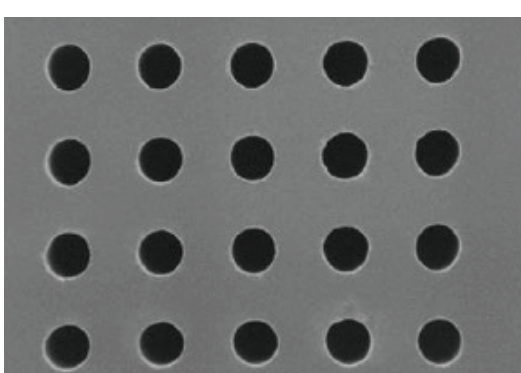
Material :Zirconia
Hole diameter : Φ 110 μ m
Thickness :330 μ m



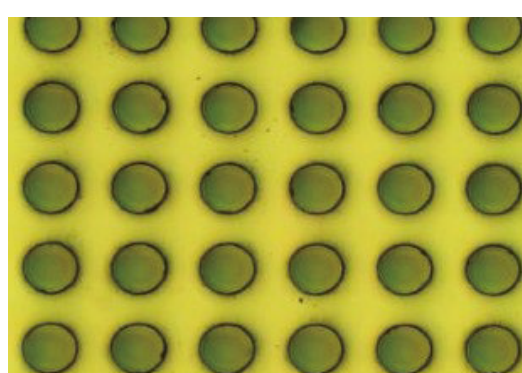
Material :Aluminum Ceramics
Hole diameter : Φ 50 μ m
Thickness :300 μ m



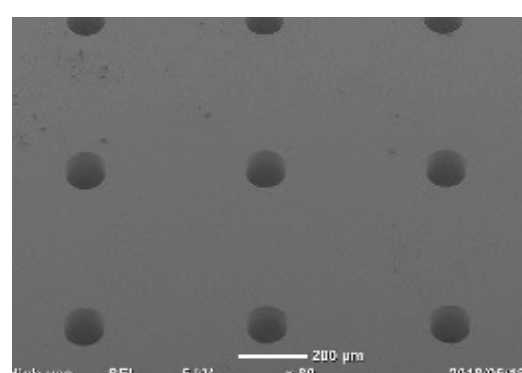
Material :Tungsten
Hole diameter : Φ 50 μ m&100 μ m
Thickness :500 μ m



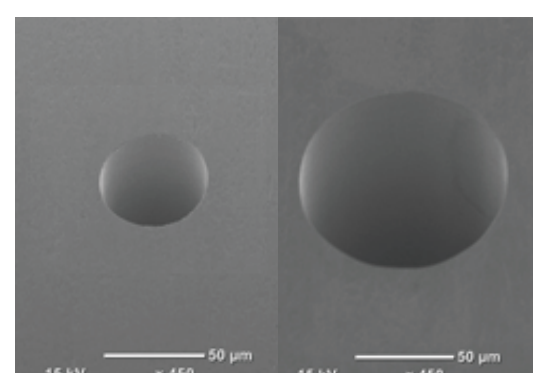
Material :Single-Crystal Silicon
Hole diameter : Φ 100 μ m
Thickness :300 μ m



Material :Synthetic silica
Hole diameter : Φ 90 μ m
Thickness :500 μ m



Material :PET
Hole diameter : Φ 50 μ m
Thickness :188 μ m



Material :Polyimide
Hole diameter : Φ 50 μ m&100 μ m
Thickness :600 μ m